

ABSTRACT

A tape for semiconductor processing that can be caused to shrink by heating sufficiently in a short time period and can retain a kerf width is provided.

A tape for semiconductor processing 10 of the invention includes a temporary adhesive tape 15 having a substrate film 11; and a temporary adhesive layer 12 formed on at least one surface side of the substrate film 11, in which regarding the temporary adhesive tape 15, the sum of the sum total of the differential values of the thermal deformation rate in the MD direction per 1°C between 40°C and 80°C measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, and the sum total of the differential values of the thermal deformation rate in the TD direction per 1°C between 40°C and 80°C measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, is a negative value.